



**THE DATASHEET OF  
SN74ALVCH16823DLR**



## FEATURES

- Member of the Texas Instruments Widebus™ Family
- EPIC™ (Enhanced-Performance Implanted CMOS) Submicron Process
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages

## DESCRIPTION

This 18-bit bus-interface flip-flop is designed for 1.65-V to 3.6-V  $V_{CC}$  operation.

The SN74ALVCH16823 features 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. This device is particularly suitable for implementing wider buffer registers, I/O ports, bidirectional bus drivers with parity, and working registers.

The SN74ALVCH16823 can be used as two 9-bit flip-flops or one 18-bit flip-flop. With the clock-enable ( $\overline{CLKEN}$ ) input low, the D-type flip-flops enter data on the low-to-high transitions of the clock. Taking  $\overline{CLKEN}$  high disables the clock buffer, thus latching the outputs. Taking the clear ( $\overline{CLR}$ ) input low causes the Q outputs to go low independently of the clock.

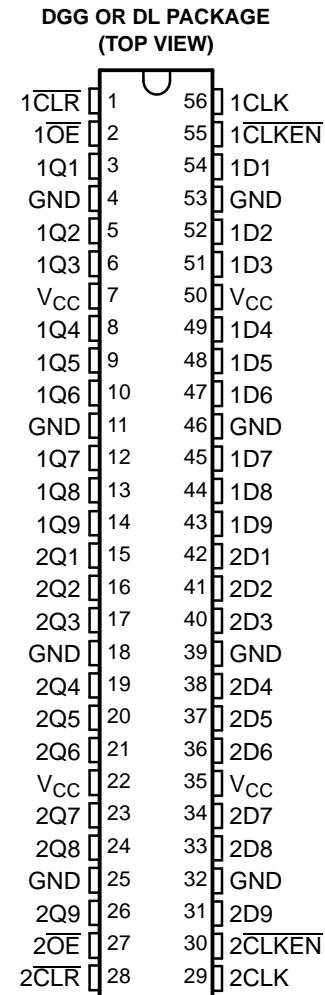
A buffered output-enable ( $\overline{OE}$ ) input can be used to place the nine outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

The output-enable ( $\overline{OE}$ ) input does not affect the internal operation of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH16823 is characterized for operation from  $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ .



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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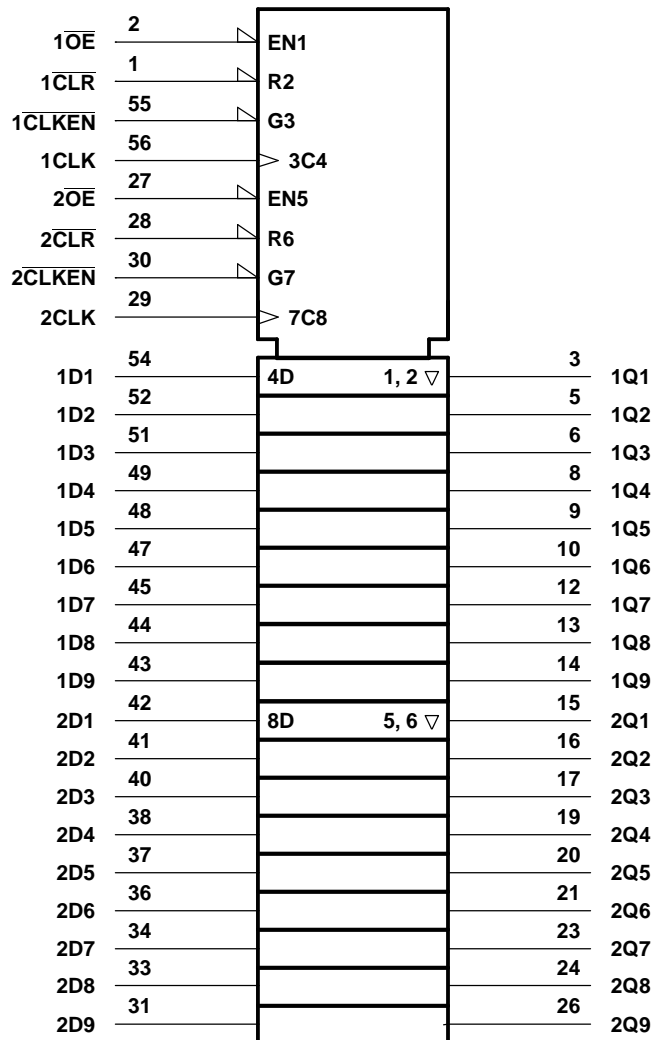
**SN74ALVCH16823**  
**18-BIT BUS-INTERFACE FLIP-FLOP**  
**WITH 3-STATE OUTPUTS**

SCES038F—JULY 1995—REVISED APRIL 2005

**FUNCTION TABLE**  
**(each 9-bit flip-flop)**

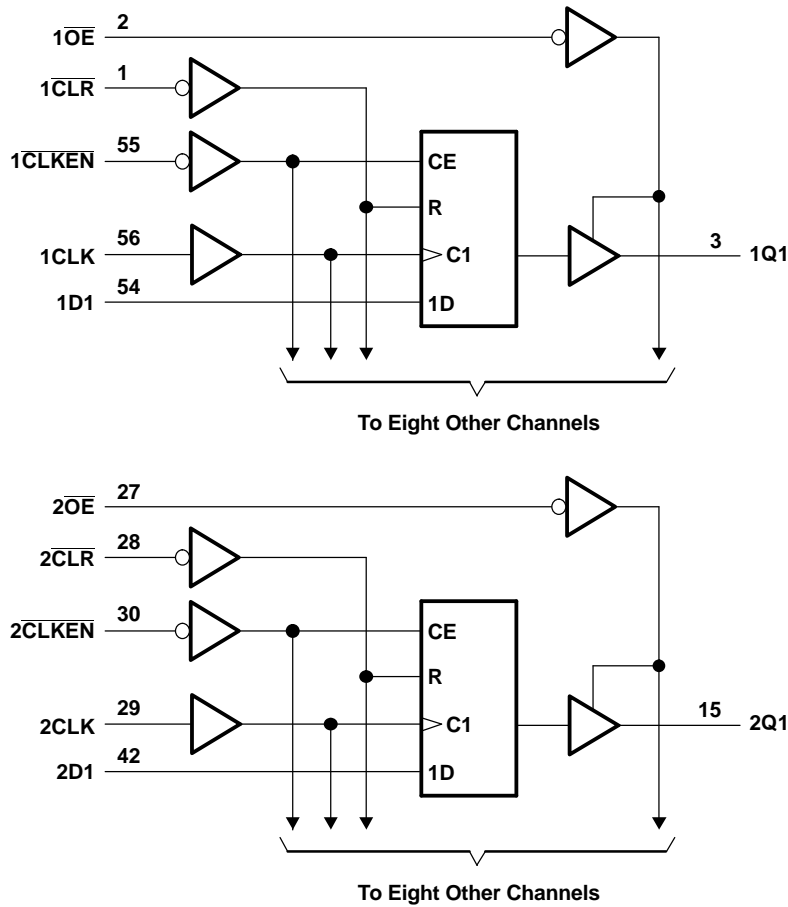
INPUTS					OUTPUT Q
$\overline{OE}$	$\overline{CLR}$	$\overline{CLKEN}$	CLK	D	
L	L	X	X	X	L
L	H	L	↑	H	H
L	H	L	↑	L	L
L	H	L	L	X	Q <sub>0</sub>
L	H	H	X	X	Q <sub>0</sub>
H	X	X	X	X	Z

**LOGIC SYMBOL<sup>(1)</sup>**



(1) This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

**LOGIC DIAGRAM (POSITIVE LOGIC)**



**Absolute Maximum Ratings<sup>(1)</sup>**

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	-0.5	4.6	V
$V_I$	Input voltage range <sup>(2)</sup>	-0.5	4.6	V
$V_O$	Output voltage range <sup>(2)(3)</sup>	-0.5	$V_{CC} + 0.5$	V
$I_{IK}$	Input clamp current		-50	mA
$I_{OK}$	Output clamp current		-50	mA
$I_O$	Continuous output current		±50	mA
	Continuous current through $V_{CC}$ or GND		±100	mA
$\theta_{JA}$	Package thermal impedance <sup>(4)</sup>		81	°C/W
			74	
$T_{stg}$	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 4.6 V maximum.
- (4) The package thermal impedance is calculated in accordance with JESD 51.

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**Recommended Operating Conditions<sup>(1)</sup>**

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage	1.65	3.6	V
$V_{IH}$	High-level input voltage	$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	$0.65 \times V_{CC}$	V
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	1.7	
		$V_{CC} = 2.7\text{ V to }3.6\text{ V}$	2	
$V_{IL}$	Low-level input voltage	$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	0.7	
		$V_{CC} = 2.7\text{ V to }3.6\text{ V}$	0.8	
$V_I$	Input voltage	0	$V_{CC}$	V
$V_O$	Output voltage	0	$V_{CC}$	V
$I_{OH}$	High-level output current	$V_{CC} = 1.65\text{ V}$	–4	mA
		$V_{CC} = 2.3\text{ V}$	–12	
		$V_{CC} = 2.7\text{ V}$	–12	
		$V_{CC} = 3\text{ V}$	–24	
$I_{OL}$	Low-level output current	$V_{CC} = 1.65\text{ V}$	4	mA
		$V_{CC} = 2.3\text{ V}$	12	
		$V_{CC} = 2.7\text{ V}$	12	
		$V_{CC} = 3\text{ V}$	24	
$\Delta t/\Delta v$	Input transition rise or fall rate		10	ns/V
$T_A$	Operating free-air temperature	–40	85	°C

(1) All unused control inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT
V <sub>OH</sub>	I <sub>OH</sub> = -100 μA	1.65 V to 3.6 V	V <sub>CC</sub> - 0.2			V
	I <sub>OH</sub> = -4 mA	1.65 V	1.2			
	I <sub>OH</sub> = -6 mA	2.3 V	2			
	I <sub>OH</sub> = -12 mA	2.3 V	1.7			
		2.7 V	2.2			
		3 V	2.4			
I <sub>OH</sub> = -24 mA	3 V	2				
V <sub>OL</sub>	I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V			0.2	V
	I <sub>OL</sub> = 4 mA	1.65 V			0.45	
	I <sub>OL</sub> = 6 mA	2.3 V			0.4	
	I <sub>OL</sub> = 12 mA	2.3 V			0.7	
		2.7 V			0.4	
	I <sub>OL</sub> = 24 mA	3 V			0.55	
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.6 V			±5	μA
I <sub>I(hold)</sub>	V <sub>I</sub> = 0.58 V	1.65 V	25			μA
	V <sub>I</sub> = 1.07 V	1.65 V	-25			
	V <sub>I</sub> = 0.7 V	2.3 V	45			
	V <sub>I</sub> = 1.7 V	2.3 V	-45			
	V <sub>I</sub> = 0.8 V	3 V	75			
	V <sub>I</sub> = 2 V	3 V	-75			
	V <sub>I</sub> = 0 to 3.6 V <sup>(2)</sup>	3.6 V			±500	
I <sub>OZ</sub>	V <sub>O</sub> = V <sub>CC</sub> or GND	3.6 V			±10	μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	3.6 V			40	μA
ΔI <sub>CC</sub>	One input at V <sub>CC</sub> - 0.6 V, Other inputs at V <sub>CC</sub> or GND	3 V to 3.6 V			750	μA
C <sub>i</sub>	Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V		4.5	pF
	Data inputs				6.5	
C <sub>O</sub>	Outputs	V <sub>O</sub> = V <sub>CC</sub> or GND	3.3 V		7	pF

 (1) All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

(2) This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

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**Timing Requirements**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

		V <sub>CC</sub> = 1.8 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f <sub>clock</sub>	Clock frequency	(1)		150		150		150		MHz
t <sub>w</sub>	Pulse duration	CLR low		(1)		3.3		3.3		ns
		CLK high or low		(1)		3.3		3.3		
t <sub>su</sub>	Setup time	CLR inactive		(1)		0.7		0.7		ns
		Data low before CLK↑		(1)		1.6		1.6		
		Data high before CLK↑		(1)		1.1		1.1		
		CLKEN low before CLK↑		(1)		1.9		1.9		
t <sub>h</sub>	Hold time	Data low after CLK↑		(1)		0.5		0.5		ns
		Data high after CLK↑		(1)		0.1		0.1		
		CLKEN low after CLK↑		(1)		0.3		0.3		

(1) This information was not available at the time of publication.

**Switching Characteristics**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 1.8 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
			MIN	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>			(1)		150		150		150		MHz
t <sub>pd</sub>	CLK	Q	(1)		1	5.8	5.2		1	4.5	ns
	CLR		(1)		1	5.4	5.2		1.2	4.6	
t <sub>en</sub>	OE	Q	(1)		1	6	5.7		1	4.8	ns
t <sub>dis</sub>	OE	Q	(1)		1.1	5.4	4.7		1.3	4.5	ns

(1) This information was not available at the time of publication.

**Switching Characteristics**

over recommended operating free-air temperature range (unless otherwise noted), V<sub>CC</sub> = 3.3 ± 0.3 V, C<sub>L</sub> = 30 pF, R<sub>L</sub> = 500 Ω

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	
f <sub>max</sub> <sup>(1)</sup>			250		MHz
t <sub>pd</sub>	CLK	Q	1	3.5	ns
	CLR		1.2	4.1	
t <sub>en</sub>	OE	Q	1	3.8	ns
t <sub>dis</sub>	OE	Q	1.3	4.5	ns
t <sub>sk(o)</sub> <sup>(1)</sup>			0.5		ns

(1) Values are characterized but not production tested.

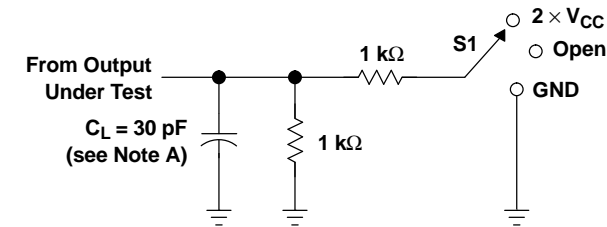
## Operating Characteristics

$T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	$V_{CC} = 1.8\text{ V}$	$V_{CC} = 2.5\text{ V}$	$V_{CC} = 3.3\text{ V}$	UNIT
			TYP	TYP	TYP	
$C_{pd}$	Power dissipation capacitance	$C_L = 50\text{ pF}, f = 10\text{ MHz}$	(1)	27	30	pF
	Outputs enabled		(1)	16	18	
	Outputs disabled					

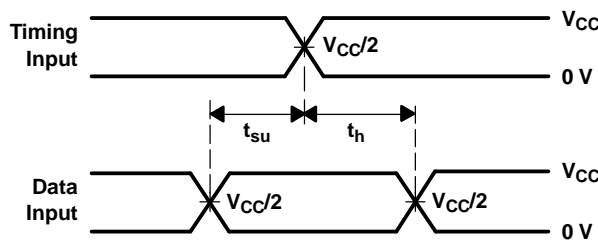
(1) This information was not available at the time of publication.

PARAMETER MEASUREMENT INFORMATION  
 $V_{CC} = 1.8\text{ V}$

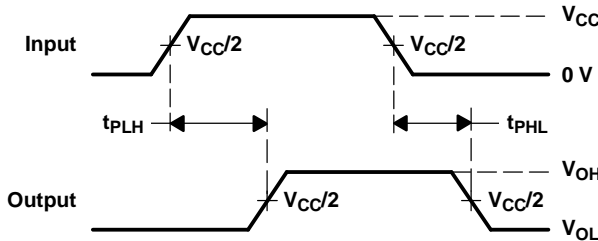


LOAD CIRCUIT

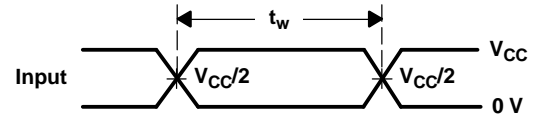
TEST	S1
$t_{pd}$	Open
$t_{PLZ}/t_{PZL}$	$2 \times V_{CC}$
$t_{PHZ}/t_{PZH}$	GND



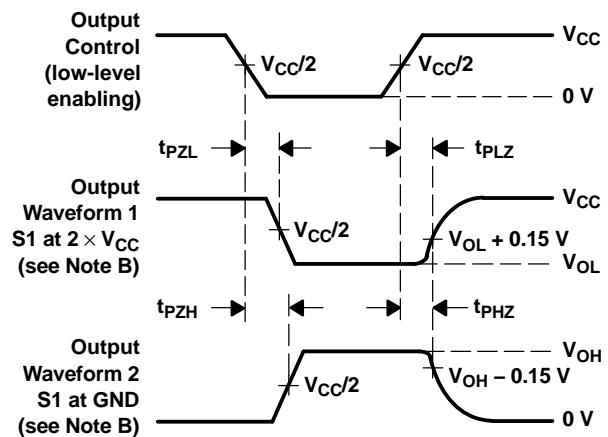
VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS  
PULSE DURATION

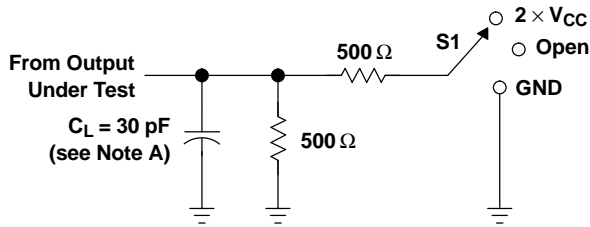


VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r \leq 2\text{ ns}$ ,  $t_f \leq 2\text{ ns}$ .  
D. The outputs are measured one at a time, with one transition per measurement.  
E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

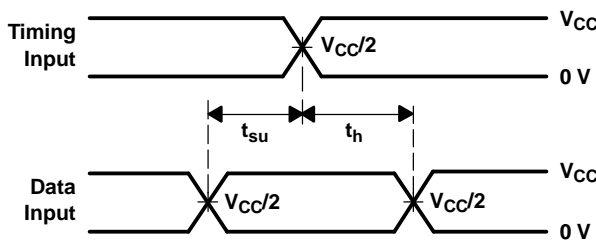
Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION  
 $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$

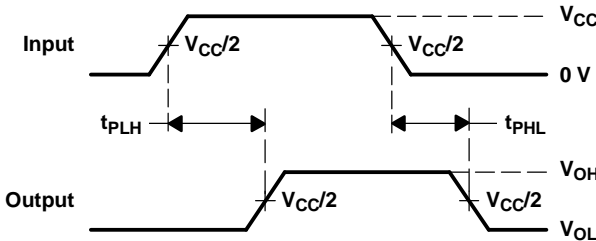


LOAD CIRCUIT

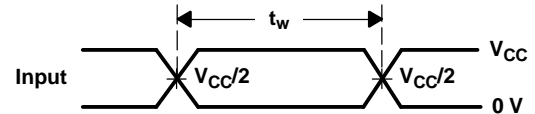
TEST	S1
$t_{pd}$	Open
$t_{PLZ}/t_{PZL}$	$2 \times V_{CC}$
$t_{PHZ}/t_{PZH}$	GND



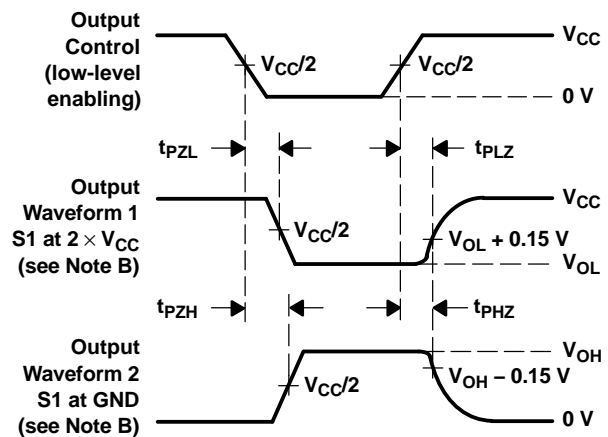
VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS  
PULSE DURATION

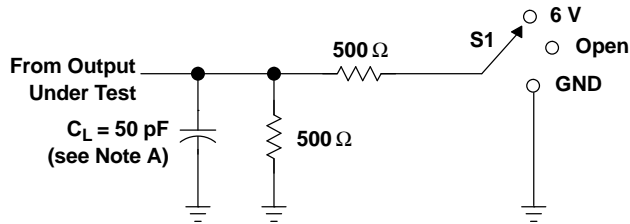


VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES

- NOTES:
- $C_L$  includes probe and jig capacitance.
  - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r \leq 2\text{ ns}$ ,  $t_f \leq 2\text{ ns}$ .
  - The outputs are measured one at a time, with one transition per measurement.
  - $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

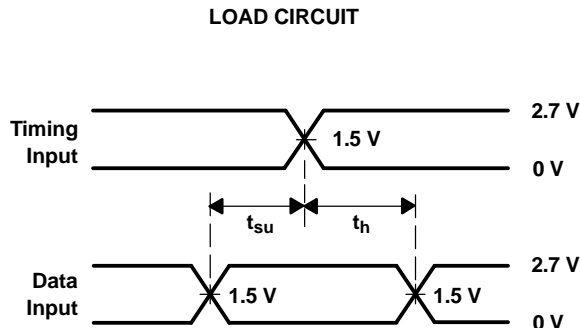
Figure 2. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION  
 $V_{CC} = 2.7\text{ V AND } 3.3\text{ V} \pm 0.3\text{ V}$

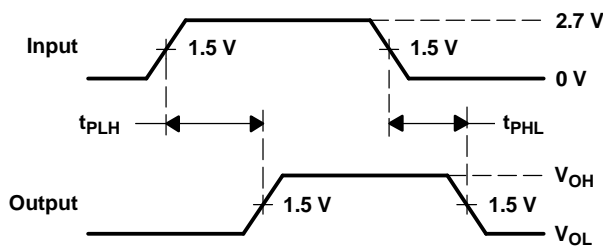


TEST	S1
$t_{pd}$	Open
$t_{PLZ}/t_{PZL}$	6 V
$t_{PHZ}/t_{PZH}$	GND

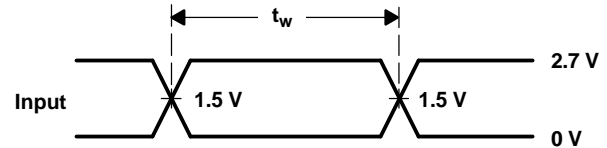
LOAD CIRCUIT



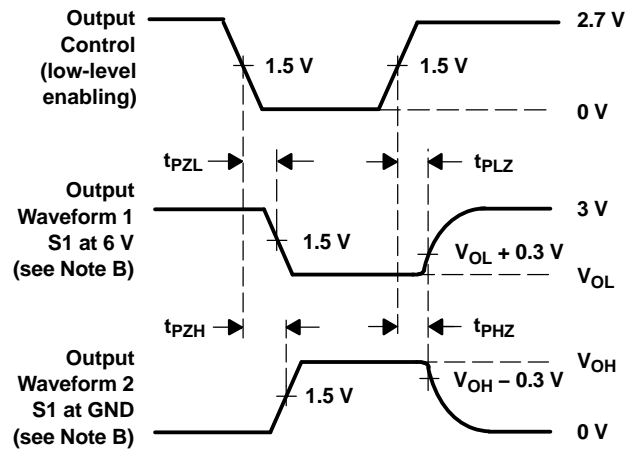
VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS  
PULSE DURATION



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r \leq 2.5\text{ ns}$ ,  $t_f \leq 2.5\text{ ns}$ .  
D. The outputs are measured one at a time, with one transition per measurement.  
E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 3. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ALVCH16823DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16823	<a href="#">Samples</a>
SN74ALVCH16823DGVR	ACTIVE	TVSOP	DGV	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	VH823	<a href="#">Samples</a>
SN74ALVCH16823DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16823	<a href="#">Samples</a>
SN74ALVCH16823DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16823	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALVCH16823DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
SN74ALVCH16823DGVR	TVSOP	DGV	56	2000	330.0	24.4	6.8	11.7	1.6	12.0	24.0	Q1
SN74ALVCH16823DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALVCH16823DGGR	TSSOP	DGG	56	2000	367.0	367.0	45.0
SN74ALVCH16823DGVR	TVSOP	DGV	56	2000	367.0	367.0	45.0
SN74ALVCH16823DLR	SSOP	DL	56	1000	367.0	367.0	55.0

DGV (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN

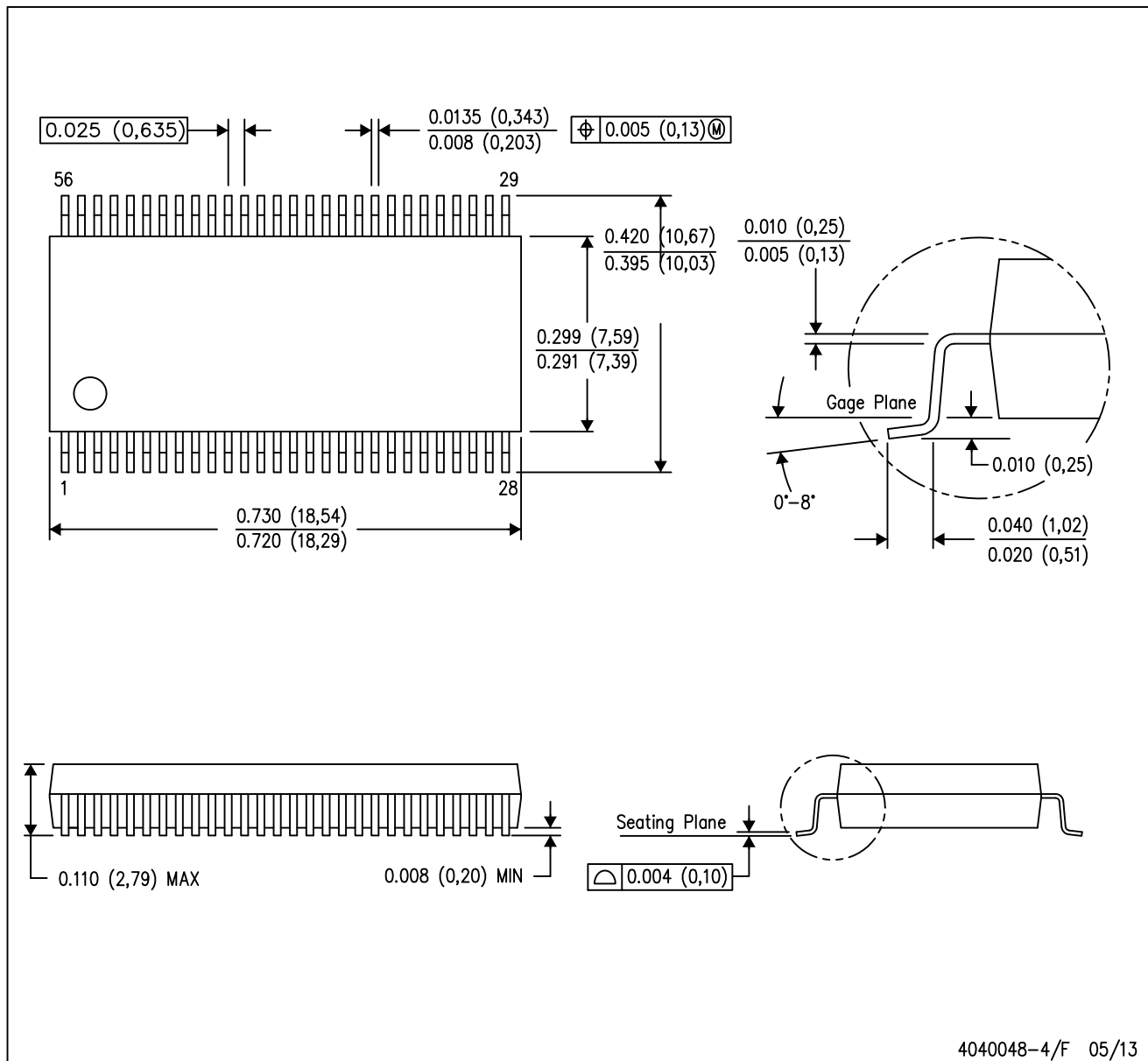


- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194

# MECHANICAL DATA

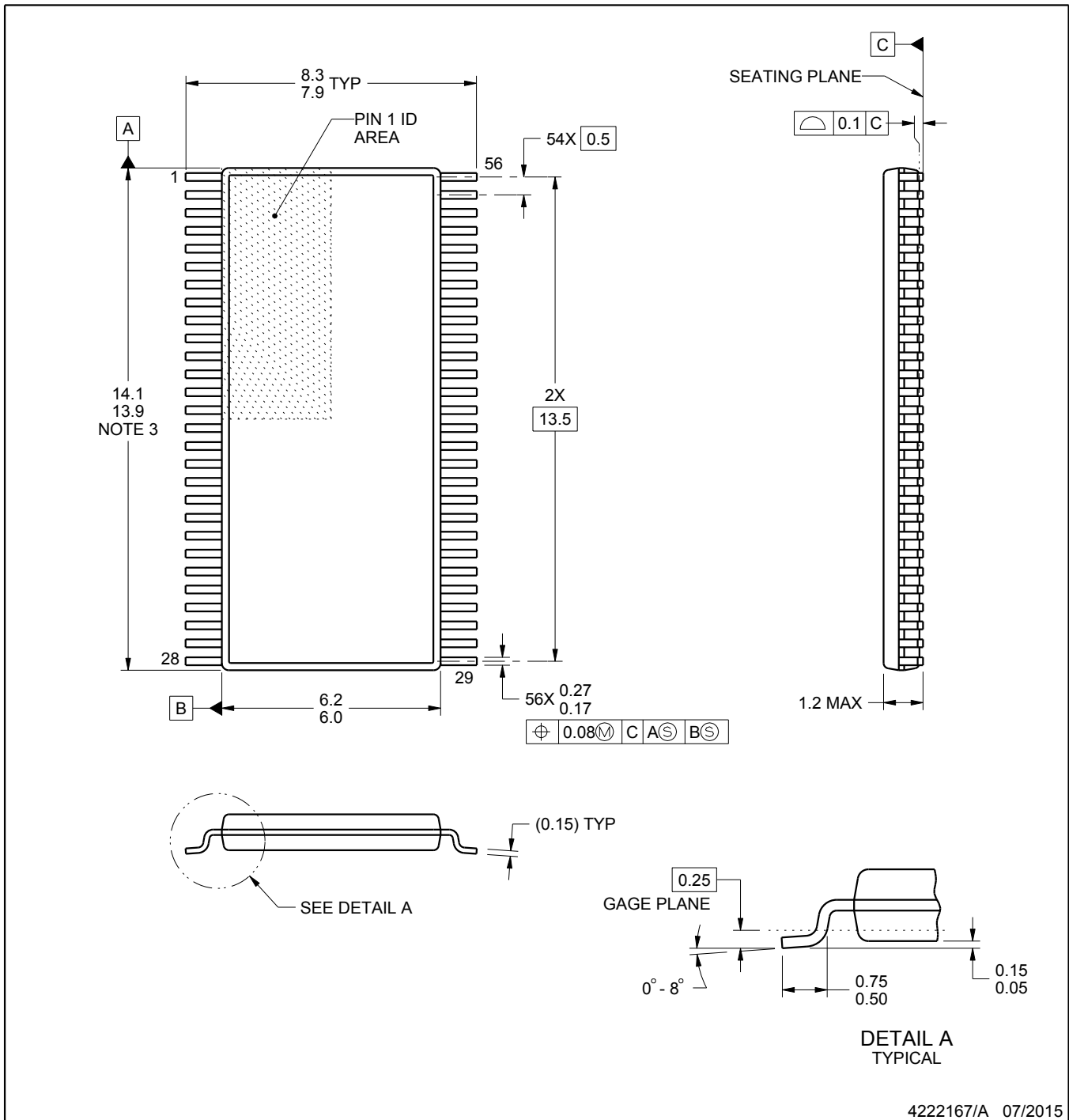
DL (R-PDSO-G56)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - Falls within JEDEC MO-118

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NOTES:

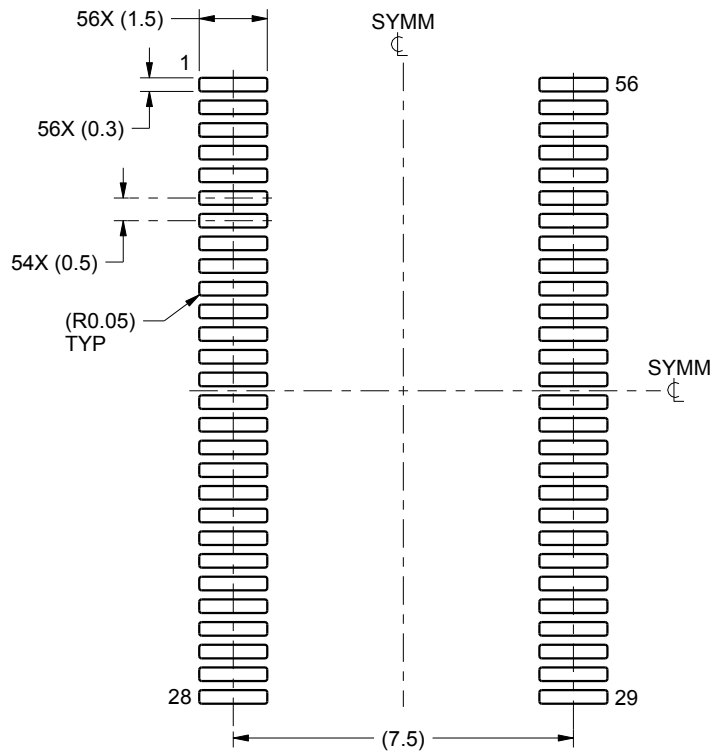
- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
- Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

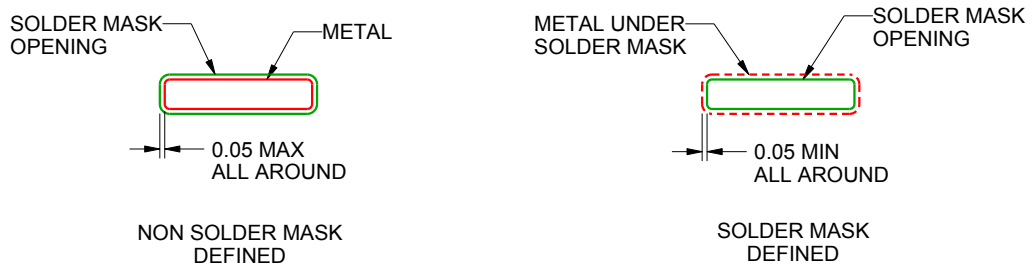
DGG0056A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

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NOTES: (continued)

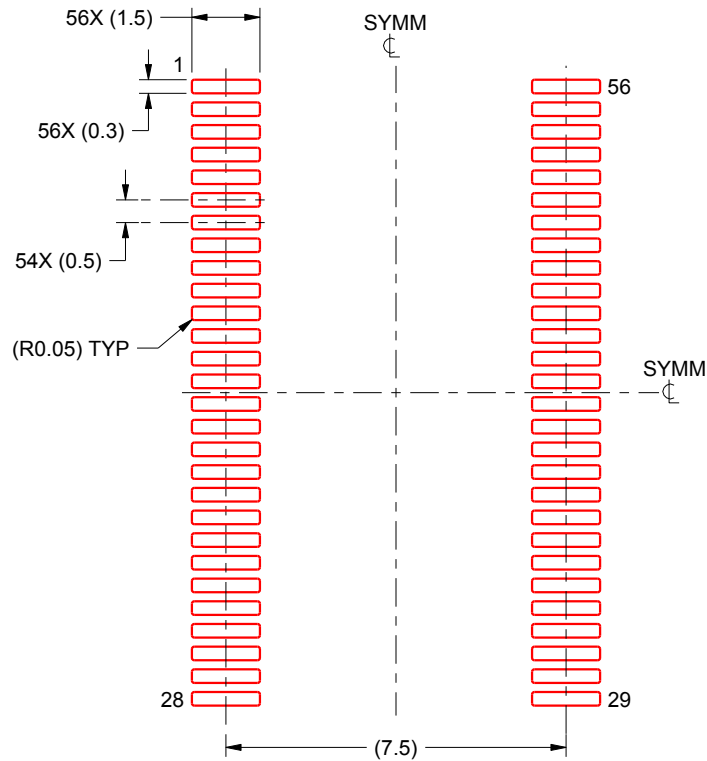
- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DGG0056A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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